

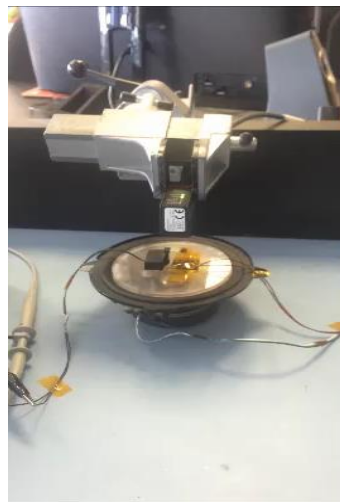
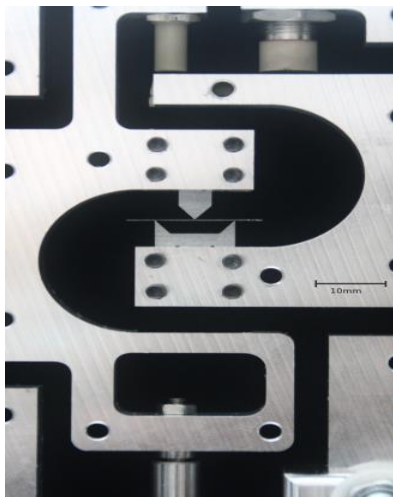
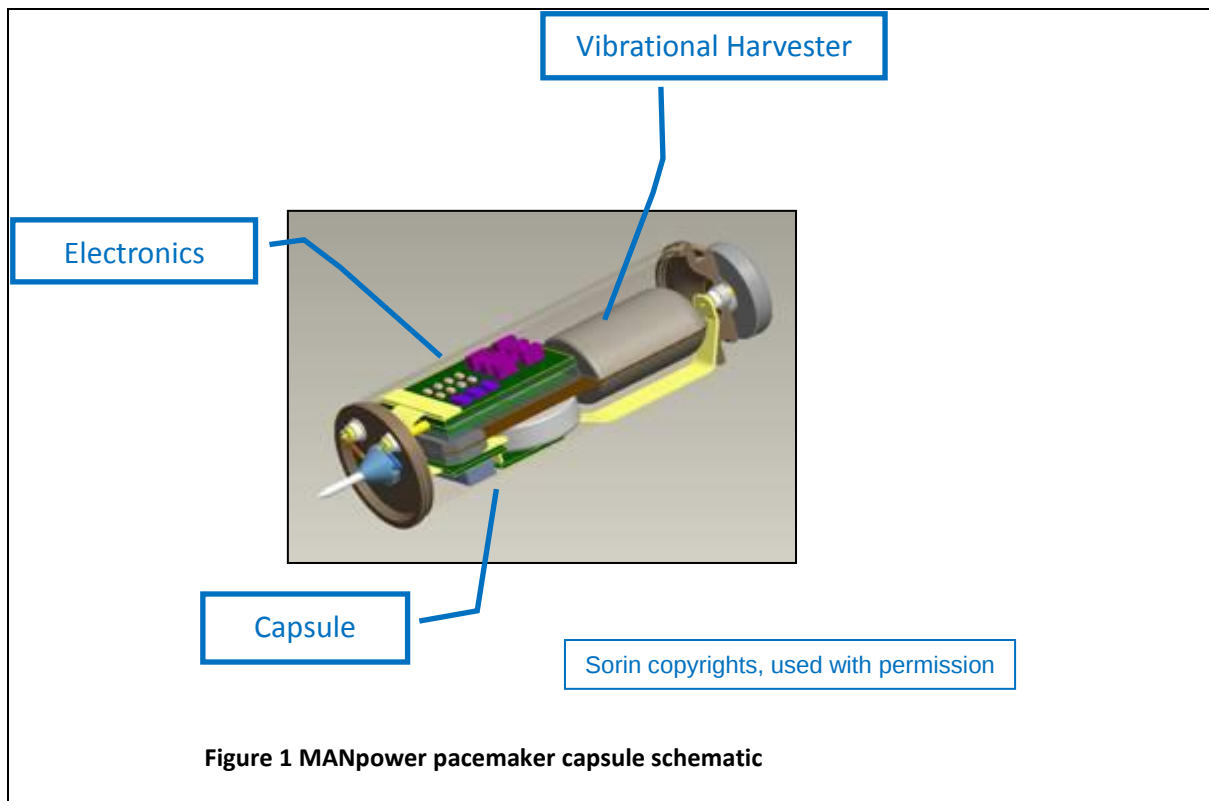
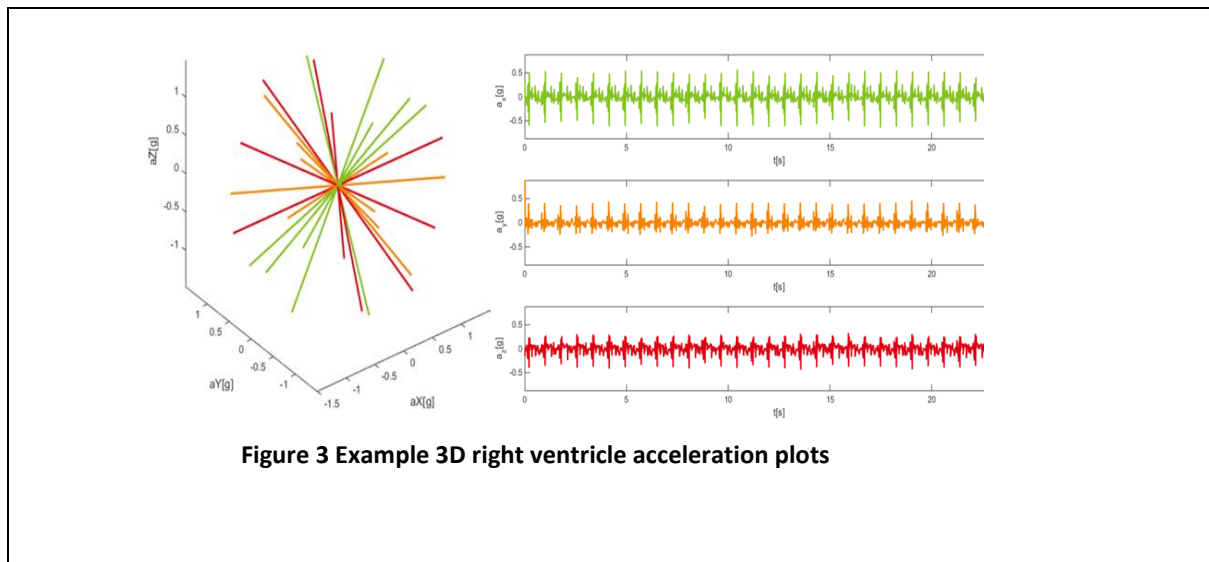


Figure 2 Customised materials testing rigs for IEF and Tyndall harvester materials

(a)



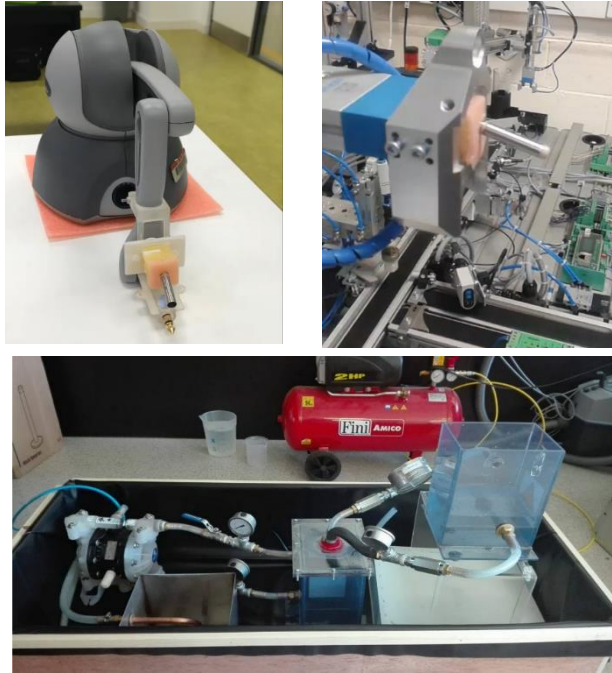


Figure 5 Robotic heartwall movement emulators

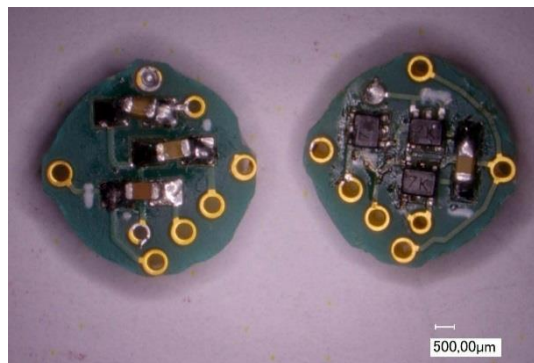


Figure 6: Photographs of the 2-cell EEH interface circuit with SMD diodes and capacitors (top and bottom) (EMFT/PSUD Copyright)

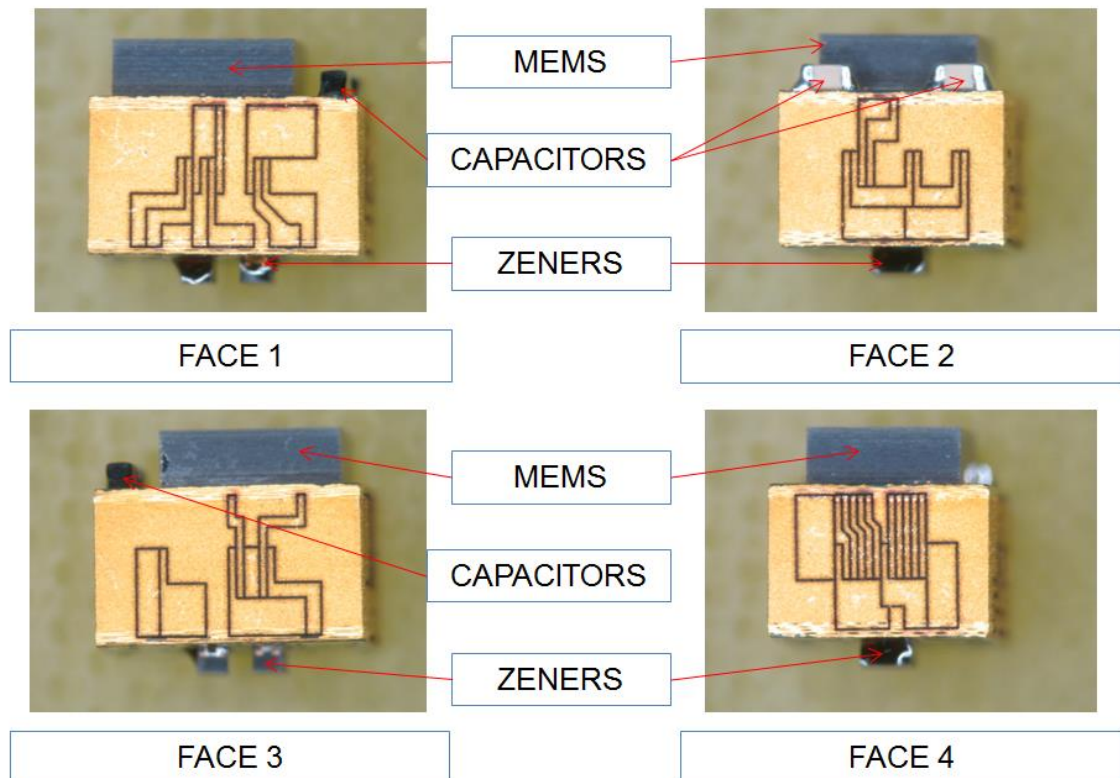


Figure 7: View of the sidewalls after integrating the electronic module by 3D-Plus innovative 3D-stacking technology. (copyright 3DPlus)

Concept for integration of different components

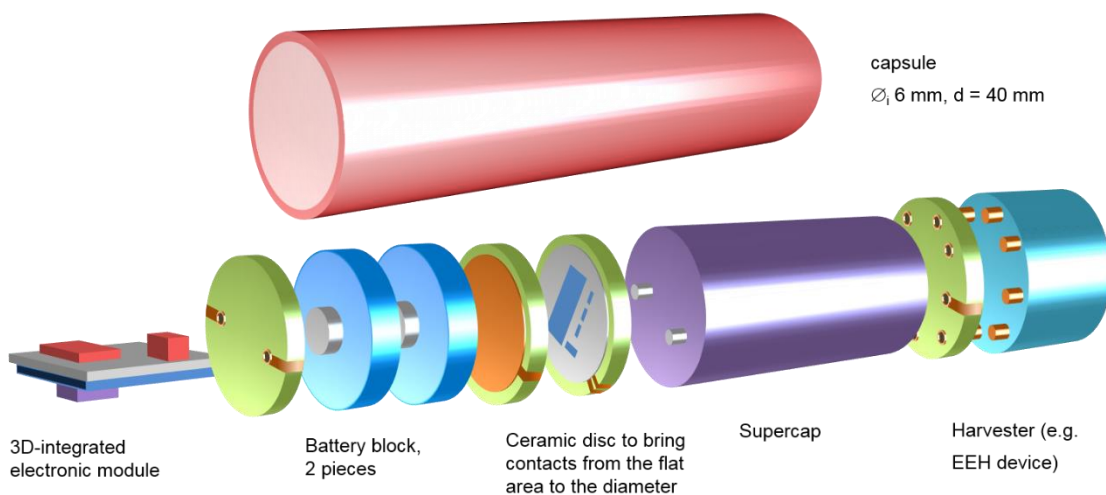


Figure 8 Concept of the overall integration of the components into the capsule using ceramic discs (copyright EMFT)

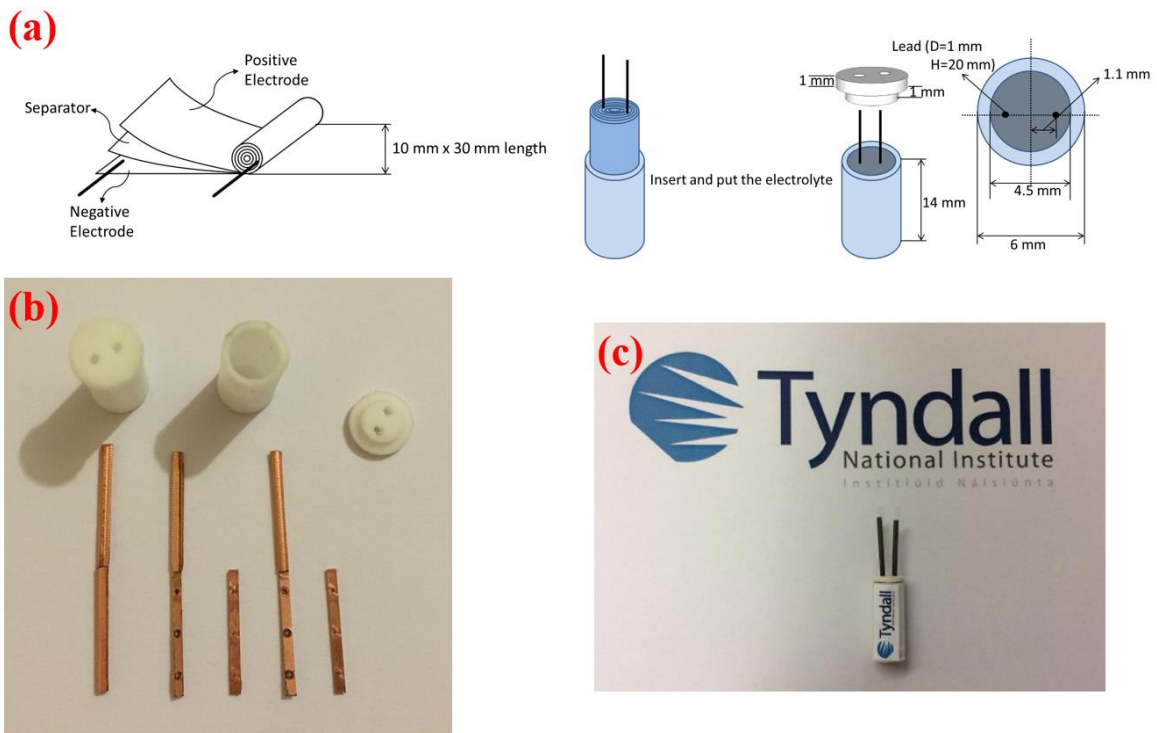


Figure 9 (a) Schematic of supercapacitor package design; (b) Photograph of each component of the package; (c) Photograph of the assembled supercapacitor. (Copyright Tyndall)

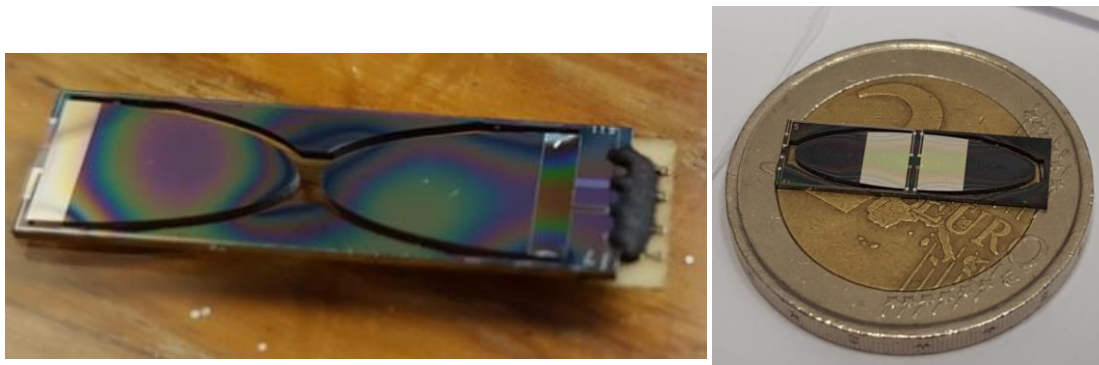


Figure 10 Pictures of the fabricated device wirebonded onto a PCB and compared to a 2 euro coin. (Copyright Tyndall)